

S8

Blade Server Passive Cooler

PRODUCT SPECIFICATIONS

Model Number: S8

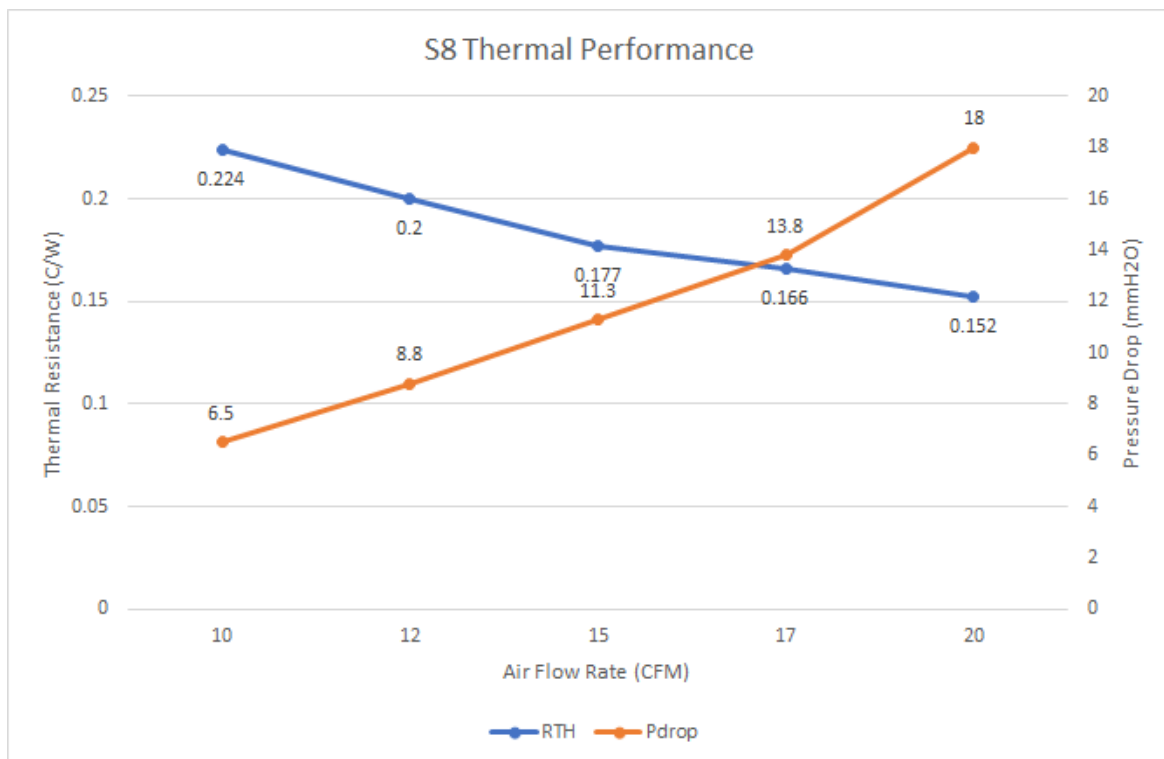
- Recommend for Intel® CPU as following
 - Intel® Sapphire Rapids Processor, Socket FCLGA 4677
- Passive Heat Sink for Blade Server or up

Overall Specification

Dimension	118 x 78 x 25.5 mm
Weight	410 g
Material	Copper Vapor Chamber and Fin Stack
Mounting sets	Intel Standard Anti-Tilt Heatsink Captive Mounting Sets
Package Carrier	PHM Package Carrier Included
Thermal Grease	Pre-Printed with SHIN-ETSU 7762 or equivalent
TDP	Support 205 Watts CPU Power Heat Dissipation

Performance Chart: S8 Thermal Resistance

Thermal Performance vs. Airflow



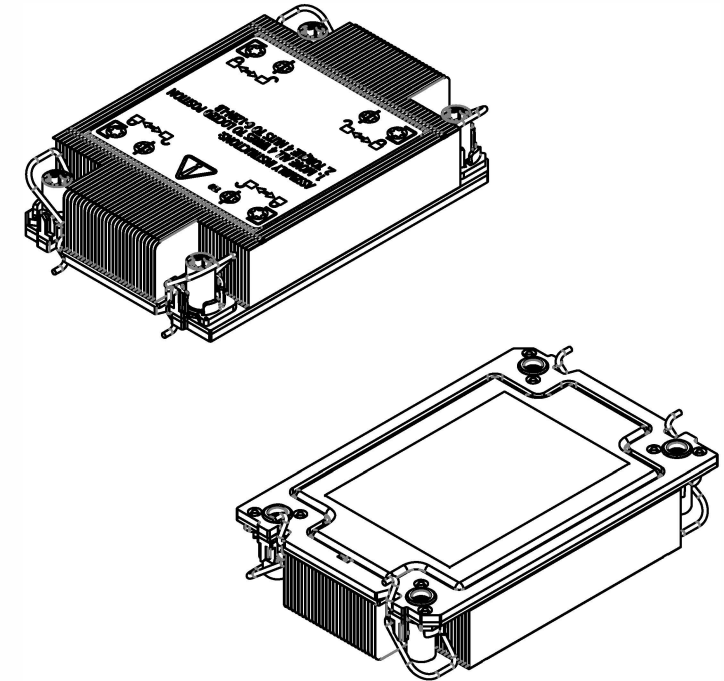
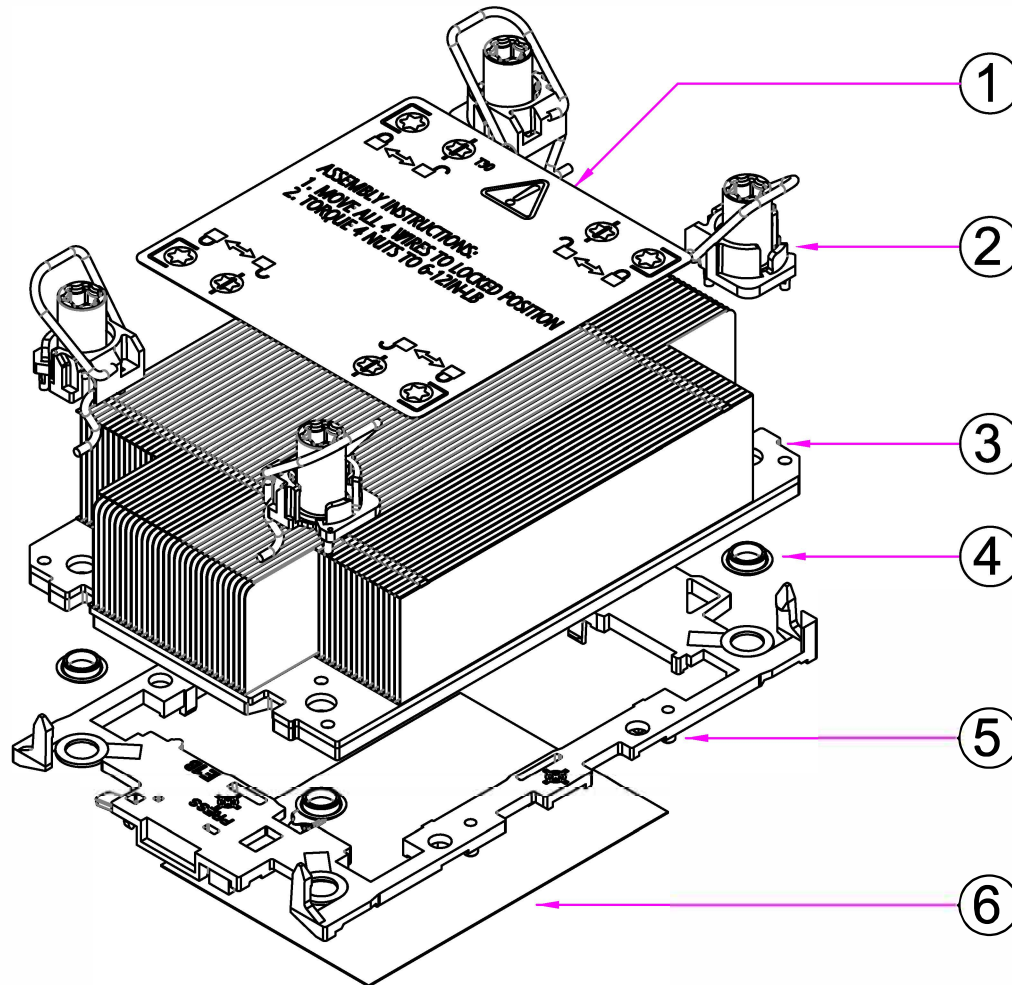
CONFIDENTIAL DOCUMENT

THIS DRAWING CONTAINS INFORMATION PROPRIETARY TO DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. ANY REPRODUCTION, DISCLOSURE, OR USE OF THIS DRAWING IS EXPRESSLY PROHIBITED EXCEPT AS DYNATRON CORPORATION AND DYNAEON INDUSTRIAL CO., LTD. MAY OTHERWISE AGREE TO IN WRITING.

REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	LANG	03/26/2021

ASSEMBLY PARTS

WHOLE SET OF HEATSINK



NOTES:

1. THE FIGURE IS FOR REFERENCE ONLY, AND NOT FOR SCALE
2. OVERALL DIMENSION : 118 x 78 x 25.5 mm
3. OVERALL WEIGHT : 520 g

6	THERMAL GREASE, PRE-PRINTED	SHIN-ETSU 7762	1
5	INTEL PACKAGE CARRIER	PLASTIC	1
4	SPACER RING	PLASTIC	4
3	HEATSINK, with STACKED FINS	COPPER FIN STACK COPPER VAPOR CHAMBER BASE STEEL RETENTION	1
2	ANTI-TILT ROTATING WIRE ASSEMBLY SET	PLASTIC NUT AND CAPTIVATION STEEL ROTATING WIRE	4
1	MOUNTING INSTRUCTION LABEL	PLASTIC	1
ITEM#	DESCRIPTION	MATERIAL	QTY.
	DATE	NAME	DYNATRON CORPORATION TITLE: 1U Passive Cooler Model S8 BOM & Exploded Assembly Drawing DWG. No: DYN-EP-S8
DRAWN	03/26/2021	E ngr	
CHECKED	03/26/2021	LANG	
ENG. APPR.			
MFG. APPR.			
QA			REV 0.0
COMMENTS:			

